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Vishay Siliconix

N-Channel 250 V (D-S) MOSFET



PRODUCT SUMMARY					
V _{DS} (V)	250				
$R_{DS(on)}$ max. (Ω) at $V_{GS} = 10 \text{ V}$	0.150				
$R_{DS(on)}$ max. (Ω) at $V_{GS} = 7.5 \text{ V}$	0.170				
Q _g typ. (nC)	8.6				
I _D (A)	12.3 ^f				
Configuration	Single				

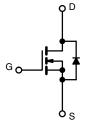
FEATURES

- TrenchFET® power MOSFET
- Low thermal resistance PowerPAK[®] package
- 100 % R_q and UIS tested
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912



APPLICATIONS

- · Primary side switch
- Synchronous rectification
- DC/DC converter
- Lighting
- Industrial



N-Channel MOSFET

ORDERING INFORMATION	
Package	PowerPAK SO-8
Lead (Pb)-free and halogen-free	Si7434ADP-T1-RE3

PARAMETER		SYMBOL	LIMIT	UNIT	
Drain-source voltage		V _{DS}	250	V	
Gate-source voltage		V _{GS}	± 20	V	
	T _C = 25 °C		12.3		
Continuous drain current (T _J = 150 °C)	T _C = 70 °C	1 , 🗀	9.8		
	T _A = 25 °C	I _D	3.7 ^{a, b}		
	T _A = 70 °C		3 a, b		
Pulsed drain current (t = 100 μs)		I _{DM}	25	Α	
Continuous source-drain diode current	T _C = 25 °C		45		
	T _A = 25 °C	I _S	4.2 ^{a, b}		
Single pulse avalanche current	L = 0.1 mH	I _{AS}	12		
Single pulse avalanche energy	L = U. I IIIH	E _{AS}	7.2	mJ	
	T _C = 25 °C		54.3		
Marriagona a construir discipation	T _C = 70 °C		34.8	14/	
Maximum power dissipation	T _A = 25 °C	P _D	5 a, b	W	
	T _A = 70 °C		3.2 ^{a, b}		
Operating junction and storage temperature	T _J , T _{stg}	-55 to +150	°C		
Soldering recommendations (peak tempera		260			

THERMAL RESISTANCE RATINGS						
PARAMETER		SYMBOL	TYPICAL	MAXIMUM	UNIT	
Maximum junction-to-ambient ^a	t ≤ 10 s	R _{thJA}	20	25	°C/W	
Maximum junction-to-case (drain)	Steady state	R _{thJC}	1.8	2.3] C/VV	

Notes

- a. Surface mounted on 1" x 1" FR4 board
- b. t = 10 s
- c. See solder profile (www.vishay.com/doc?73257). The PowerPAK SO-8 is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection
- d. Rework conditions: manual soldering with a soldering iron is not recommended for leadless components
- e. Maximum under steady state conditions is 65 °C/W
- f. $T_C = 25$ °C



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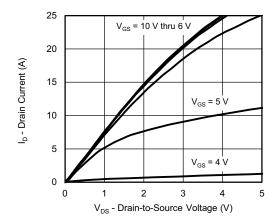
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Static					•	
Drain-source breakdown voltage	V_{DS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	250	-	-	V
V _{DS} temperature coefficient	$\Delta V_{DS}/T_{J}$	J 050 A	-	254	-	
V _{GS(th)} temperature coefficient	$\Delta V_{GS(th)}/T_J$	I _D = 250 μA	-	-6.9	-	mV/°C
Gate-source threshold voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	2	-	4	٧
Gate-source leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$	-	-	100	nA
7		V _{DS} = 250 V, V _{GS} = 0 V	-	-	1	
Zero gate voltage drain current	I _{DSS}	V _{DS} = 250 V, V _{GS} = 0 V, T _J = 70 °C	ī	-	10	μA
On-state drain current ^a	I _{D(on)}	$V_{DS} \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	10	-	-	Α
Desire a constant de contrata de la contrata del contrata del contrata de la contrata del contrata de la contrata de la contrata del contrata de la contrata del contrata de la contrata de la contrata de la contrata de la contrata del contrata de la contrata de la contrata del contrata del contrata del contrata de la contrata de la contrata de la con		$V_{GS} = 10 \text{ V}, I_D = 3.7 \text{ A}$	-	0.125	0.150	
Drain-source on-state resistance ^a	R _{DS(on)}	$V_{GS} = 7.5 \text{ V}, I_D = 3.5 \text{ A}$	-	0.135	0.170	Ω
Forward transconductance a	9 _{fs}	$V_{DS} = 15 \text{ V}, I_D = 3.7 \text{ A}$	-	10	-	S
Dynamic ^b					•	
Input capacitance	C _{iss}		-	600	-	
Output capacitance	C _{oss}	$V_{DS} = 125 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		65	-	pF
Reverse transfer capacitance	C _{rss}	-		2	-	1 .
		V _{DS} = 125 V, V _{GS} = 10 V, I _D = 2 A	-	10.9	16.5	
Total gate charge	Q_g			8.6	12.9	
Gate-source charge	Q _{qs}	$V_{DS} = 125 \text{ V}, V_{GS} = 7.5 \text{ V}, I_D = 2 \text{ A}$	-	2.7	-	nC
Gate-drain charge	Q_{gd}			2.9	-	
Output charge	Q _{oss}	V _{DS} = 125 V, V _{GS} = 0 V	-	30	45	
Gate resistance	R_g	f = 1 MHz	0.5	2.3	4.6	Ω
Turn-on delay time	t _{d(on)}		-	8	16	
Rise time	t _r	V_{DD} = 125 V, R_L = 41.7 Ω , $I_D \cong 3$ A,	-	22	35	
Turn-off delay time	t _{d(off)}	$V_{GEN} = 10 \text{ V}, R_g = 1 \Omega$		18	30	-
Fall time	t _f		-	22	35	
Turn-on delay time	t _{d(on)}		-	10	20	ns
Rise time	t _r	$V_{DD} = 125 \text{ V}, R_1 = 41.7 \Omega, I_D \cong 3 \text{ A},$	-	22	40	
Turn-off delay time	t _{d(off)}	$V_{GEN} = 7.5 \text{ V}, R_g = 1 \Omega$	-	18	30	
Fall time	t _f		-	25	50	
Drain-Source Body Diode Characteristi	cs			L		
Continuous source-drain diode current	I _S	T _C = 25 °C	-		45	
Pulse diode forward current	I _{SM}	-	-	-	25	Α
Body diode voltage	V _{SD}	I _S = 3.4 A, V _{GS} = 0 V	-	0.8	1.2	٧
Body diode reverse recovery time	t _{rr}		-	100	150	ns
Body diode reverse recovery charge	Q _{rr}		-	356	550	nC
Reverse recovery fall time	t_a $I_F = 3.4 \text{ A, di/dt} = 100 \text{ A/µs, T}_J = 25 °C $		65	-		
Reverse recovery rise time	t _b		-	35	-	ns

Notes

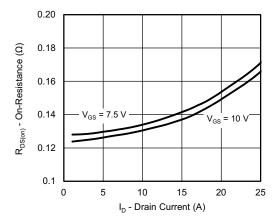
- a. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%$
- b. Guaranteed by design, not subject to production testing

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

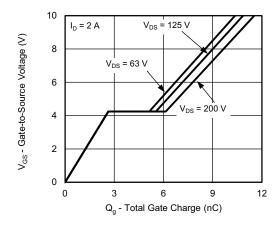




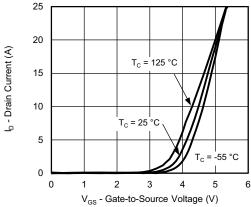
Output Characteristics



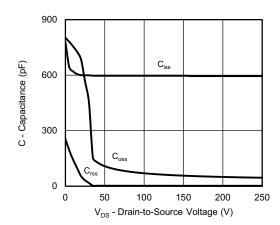
On-Resistance vs. Drain Current and Gate Voltage



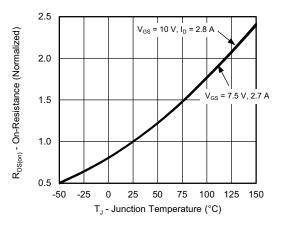
Gate Charge



Transfer Characteristics

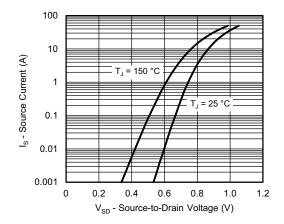


Capacitance

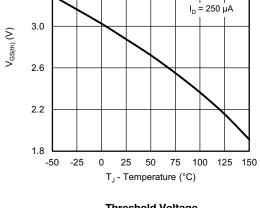


On-Resistance vs. Junction Temperature



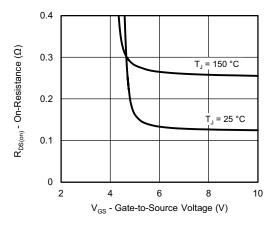


Source-Drain Diode Forward Voltage

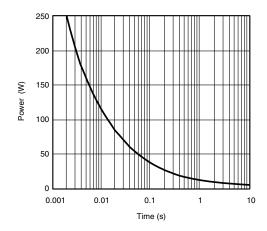


3.4

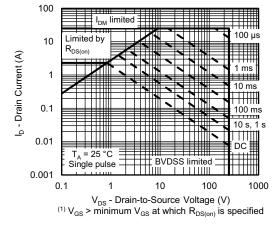
Threshold Voltage



On-Resistance vs. Gate-to-Source Voltage

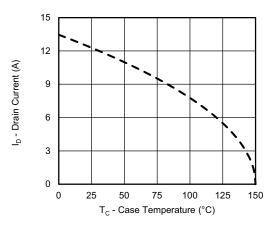


Single Pulse Power, Junction-to-Ambient

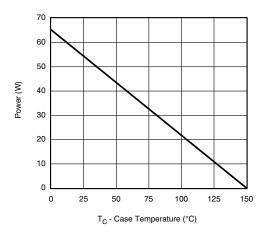


Safe Operating Area, Junction-to-Ambient

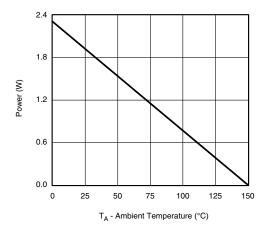




Current Derating a





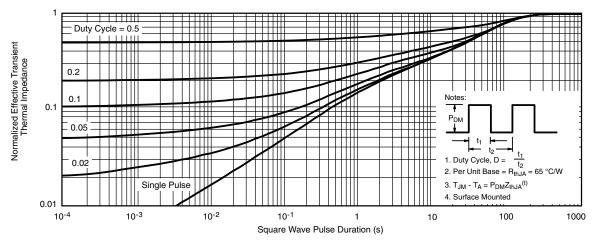


Power, Junction-to-Ambient

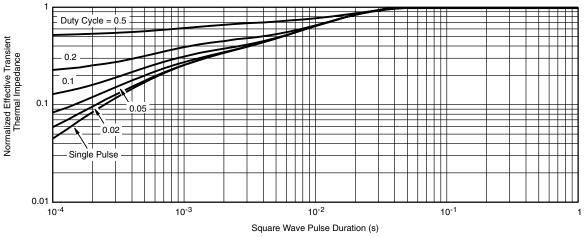
Note

a. The power dissipation P_D is based on T_J max. = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit





Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Foot

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package / tape drawings, part marking, and reliability data, see www.vishay.com/ppg?75843.



DWG: 5881

PowerPAK® SO-8, (Single/Dual)

Notes 1. Inch will govern. 2 Dimensions exclusive of mold gate burrs.

3. Dimensions exclusive of mold flash and cutting burrs.

Backside View of Dual Pad

DIM.		MILLIMETERS			INCHES		
	MIN.	NOM.	MAX.	MIN.	NOM.	MAX	
Α	0.97	1.04	1.12	0.038	0.041	0.044	
A1		-	0.05	0	_	0.002	
b	0.33	0.41	0.51	0.013	0.016	0.020	
С	0.23	0.28	0.33	0.009	0.011	0.013	
D	5.05	5.15	5.26	0.199	0.203	0.207	
D1	4.80	4.90	5.00	0.189	0.193	0.197	
D2	3.56	3.76	3.91	0.140	0.148	0.154	
D3	1.32	1.50	1.68	0.052	0.059	0.066	
D4		0.57 typ.		0.0225 typ.			
D5		3.98 typ.			0.157 typ.		
Е	6.05	6.15	6.25	0.238	0.242	0.246	
E1	5.79	5.89	5.99	0.228	0.232	0.236	
E2	3.48	3.66	3.84	0.137	0.144	0.151	
E3	3.68	3.78	3.91	0.145	0.149	0.154	
E4		0.75 typ.			0.030 typ.		
е		1.27 BSC			0.050 BSC		
K		1.27 typ.		0.050 typ.			
K1	0.56	-	-	0.022	-	-	
Н	0.51	0.61	0.71	0.020	0.024	0.028	
L	0.51	0.61	0.71	0.020	0.024	0.028	
L1	0.06	0.13	0.20	0.002	0.005	0.008	
θ	0°	-	12°	0°	-	12°	
W	0.15	0.25	0.36	0.006	0.010	0.014	
М	0.125 typ.			0.005 typ.			

Revison: 13-Feb-17 1 Document Number: 71655



RECOMMENDED MINIMUM PADS FOR PowerPAK® SO-8 Single



Recommended Minimum Pads Dimensions in Inches/(mm)

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APPLICATION NOTE



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